

## MSF2N60

### 600V N-Channel MOSFET

#### Description

The MSF2N60 is a N-channel enhancement-mode MOSFET , providing the designer with the best combination of fast switching, ruggedized device design, low on-resistance and cost effectiveness. The ITO-220AB package is universally preferred for all commercial-industrial applications

#### Features

- Low On Resistance
- Simple Drive Requirement
- Low Gate Charge
- Fast Switching Characteristic
- RoHS compliant package

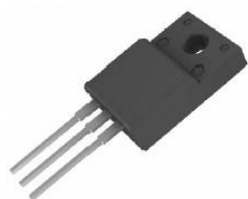
#### Application

- Open Framed Power Supply
- Adapter
- STB

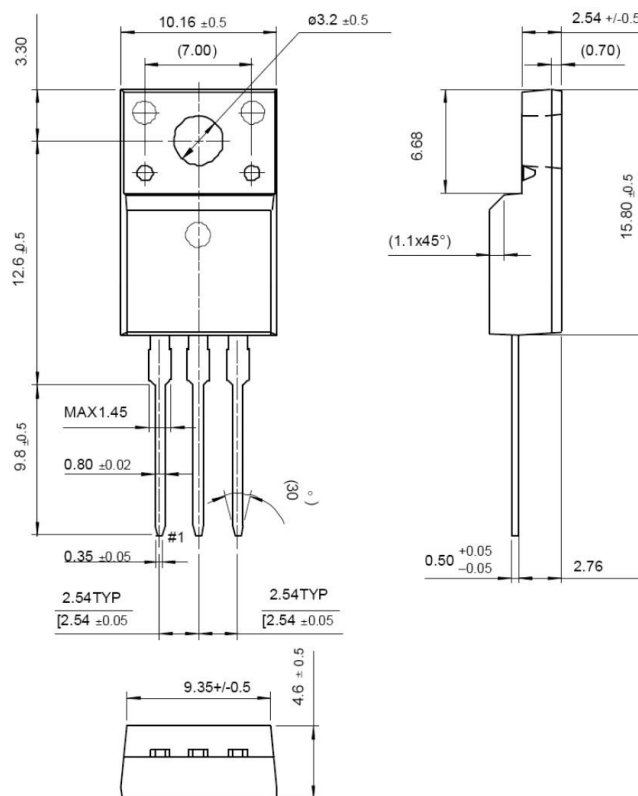
**Package type :** ITO220-AB

#### Packing & Order Information

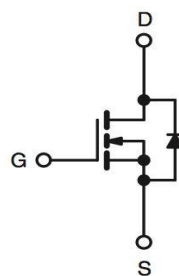
50/Tube ; 1,000/Box



**RoHS**  
COMPLIANT



#### Graphic symbol



### MAXIMUM RATINGS AND ELECTRICAL CHARACTERISTICS

#### Absolute Maximum Ratings

Symbol	Parameter	Value	Unit
$V_{DS}$	Drain-Source Voltage	600	V
$V_{GS}$	Gate-Source Voltage	$\pm 30$	V
$I_D$	Drain Current -Continuous ( $T_C=25^{\circ}C$ )	2.0	A
	Drain Current -Continuous ( $T_C=100^{\circ}C$ )	1.3	A
$I_{DM}$	Drain Current Pulsed	8.0	A
$E_{AS}$	Single Pulsed Avalanche Energy	120	mJ
$E_{AR}$	Repetitive Avalanche Energy	5.4	mJ
$dv/dt$	Peak Diode Recovery $dv/dt$	4.5	V/ns
$T_J, T_{STG}$	Operating and Storage Temperature Range	-55 to +150	$^{\circ}C$

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#### Absolute Maximum Ratings

Symbol	Parameter	Value	Unit
$P_D$	Total Power Dissipation ( $T_C = 25^\circ\text{C}$ )	23	W
	Derating Factor above $25^\circ\text{C}$	0.18	W/ $^\circ\text{C}$
$T_L$	Maximum lead temperature for soldering purposes, 1/8" from case for 5 seconds	300	$^\circ\text{C}$

- Drain current limited by maximum junction temperature

#### Thermal characteristics ( $T_c=25^\circ\text{C}$ unless otherwise noted)

Symbol	Parameter	Max.	Units
$R_{thjc}$	Junction-to-Case	5.5	$^\circ\text{C/W}$
$R_{\theta JA}$	Junction-to-Ambient	62.5	

#### On Characteristics

Symbol	Parameter	Test Conditions	Min	Typ.	Max.	Units
$V_{GS}$	Gate Threshold Voltage	$V_{DS} = V_{GS}, I_D = 250\mu\text{A}$	2.0	--	4.0	V
$R_{DS(ON)}$	Static Drain-Source On-Resistance	$V_{GS} = 10\text{ V}, I_D = 3.5\text{ A}$	--	4.0	4.7	$\Omega$

#### Off Characteristics

Symbol	Parameter	Test Conditions	Min	Typ.	Max.	Units
$BV_{DSS}$	Drain-Source Breakdown Voltage	$V_{GS} = 0\text{ V}, I_D = 250\mu\text{A}$	600	--	--	V
$\Delta BV_{DSS} / \Delta T_J$	Breakdown Voltage Temperature Coefficient	$I_D = 250\mu\text{A}$ , Referenced to $25^\circ\text{C}$	--	0.6	--	V/ $^\circ\text{C}$
$I_{DSS}$	Zero Gate Voltage Drain Current	$V_{DS} = 600\text{ V}, V_{GS} = 0\text{ V}$ $V_{DS} = 480\text{ V}, T_C = 125^\circ\text{C}$	--	--	10 100	$\mu\text{A}$
$I_{GSSF}$	Gate-Body Leakage Current, Forward	$V_{GS} = 30\text{ V}, V_{DS} = 0\text{ V}$	--	--	100	nA
$I_{GSSR}$	Gate-Body Leakage Current, Reverse	$V_{GS} = -30\text{ V}, V_{DS} = 0\text{ V}$	--	--	-100	nA

#### Dynamic Characteristics

Symbol	Parameter	Test Conditions	Min	Typ.	Max.	Units
$C_{ISS}$	Input Capacitance	$V_{DS} = 25\text{ V}, V_{GS} = 0\text{ V},$ $f = 1.0\text{MHz}$	--	320	420	pF
$C_{OSS}$	Output Capacitance		--	35	46	pF
$C_{RSS}$	Reverse Transfer Capacitance		--	4.5	6.0	pF
$Q_g$	Total Gate Charge	$V_{DS} = 480\text{ V}, I_D = 2\text{ A},$ $V_{GS} = 10\text{ V}$	--	9.5	13	
$Q_{gs}$	Gate-Source Charge		--	1.6	--	
$Q_{gd}$	Gate-Drain Charge		--	4.0	--	

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#### Dynamic Characteristics

Symbol	Parameter	Test Conditions	Min	Typ.	Max.	Units
$t_{d(on)}$	Turn-On Time	$V_{DS} = 300 \text{ V}, I_D = 2 \text{ A},$ $R_G = 25 \Omega$	--	8	30	ns
$t_r$	Turn-On Time		--	23	60	ns
$t_{d(off)}$	Turn-Off Delay Time		--	25	60	ns
$t_f$	Turn-Off Fall Time		--	28	70	ns

#### Source-Drain Diode Maximum Ratings and Characteristics

Symbol	Parameter	Test Conditions	Min	Typ.	Max.	Units
$I_S$	Continuous Source-Drain Diode Forward Current		--	--	2.0	A
$I_{SM}$	ISM Pulsed Source-Drain Diode Forward Current		--	--	6.0	
$V_{SD}$	Source-Drain Diode Forward Voltage	$I_S = 2 \text{ A}, V_{GS} = 0 \text{ V}$	--	--	1.4	V
$t_{rr}$	Reverse Recovery Time	$I_S = 2 \text{ A}, V_{GS} = 0 \text{ V}$ $diF/dt = 100 \text{ A}/\mu\text{s}$	--	230	--	ns
$Q_{rr}$	Reverse Recovery Charge		--	1.0	--	$\mu\text{C}$

Notes ;

1. Repetitive Rating: Pulse width limited by maximum junction temperature
2.  $L=55\text{mH}$ ,  $I_{AS}=2\text{A}$ ,  $V_{DD}=50\text{V}$ ,  $R_G=25\Omega$ , Starting  $T_J=25^\circ\text{C}$
3.  $I_{SD} \leq 2\text{A}$ ,  $di/dt \leq 200\text{A}/\mu\text{s}$ ,  $V_{DD} \leq BV_{DSS}$ , Starting  $T_J=25^\circ\text{C}$
4. Pulse Test: Pulse Width  $\leq 300 \mu\text{s}$ , Duty Cycle  $\leq 2\%$
5. Essentially Independent of Operating Temperature

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#### ■ Characteristics Curve

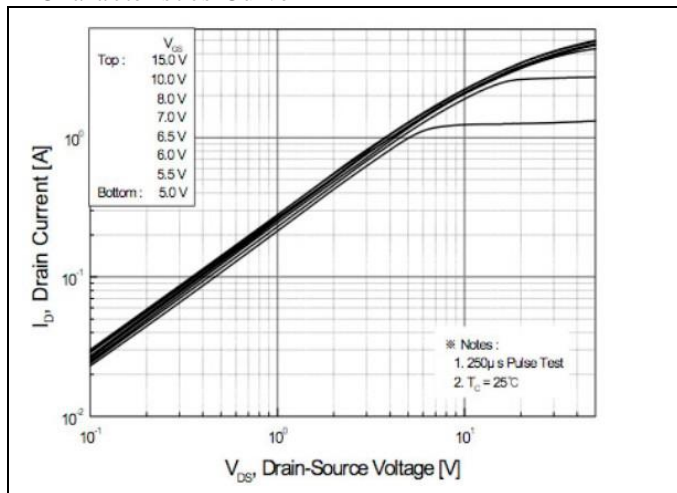


FIG.1-ON REGION CHARACTERISTICS

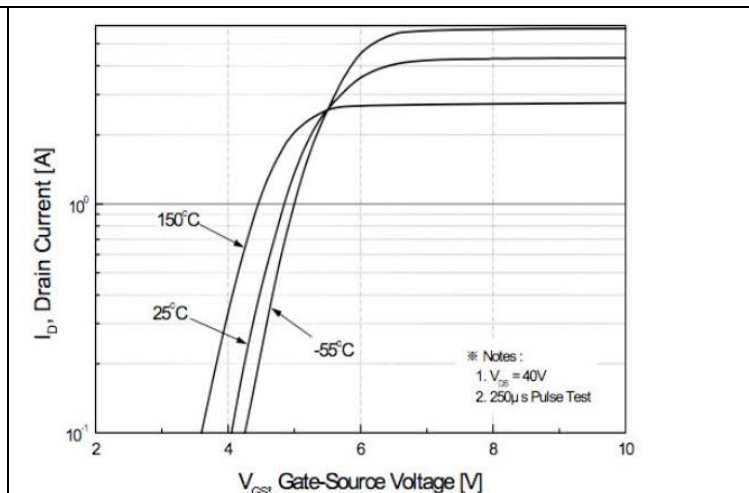


FIG.2-TRANSFER CHARACTERISTICS

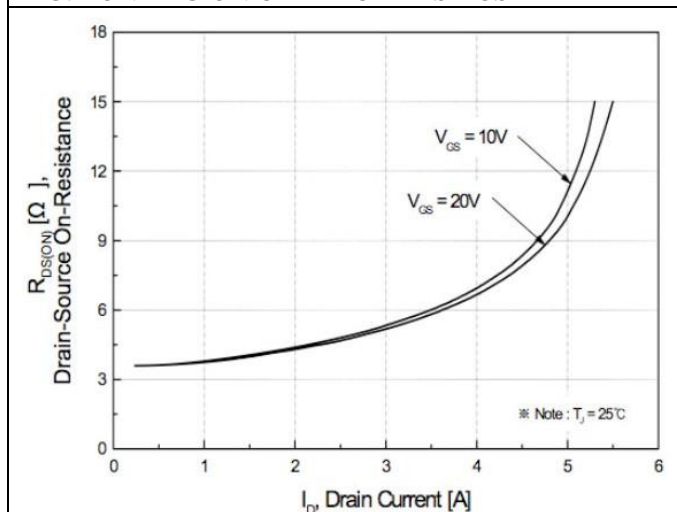


FIG.3-ON RESISTANCE VARIATION VS DRAIN CURRENT AND GATE VOLTAGE

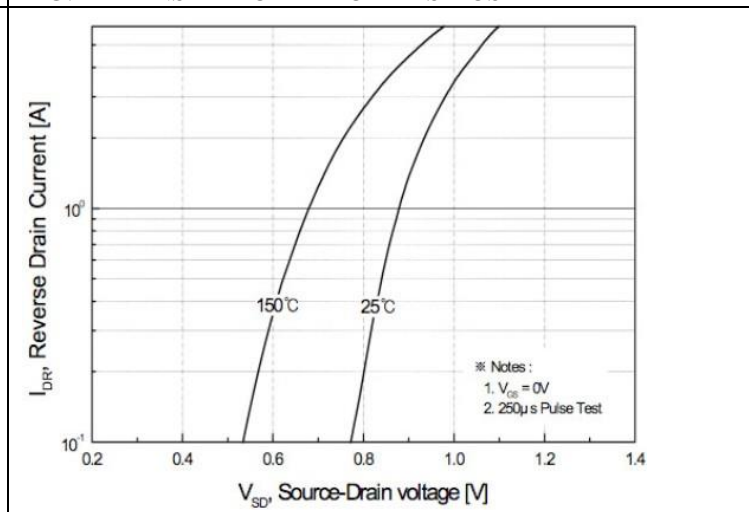


FIG.4-BODY DIODE FORWARD VOLTAGE VARIATION WITH SOURCE CURRENT AND TEMPERATURE

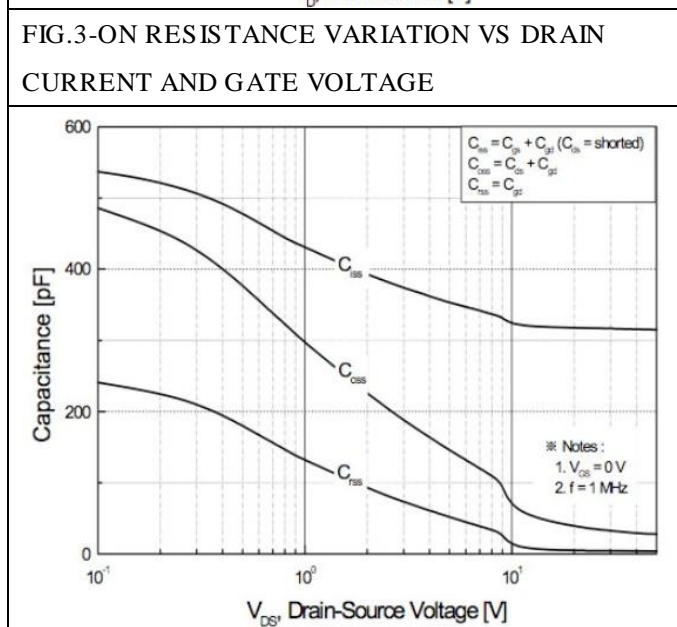


FIG.5-CAPACITANCE CHARACTERISTICS

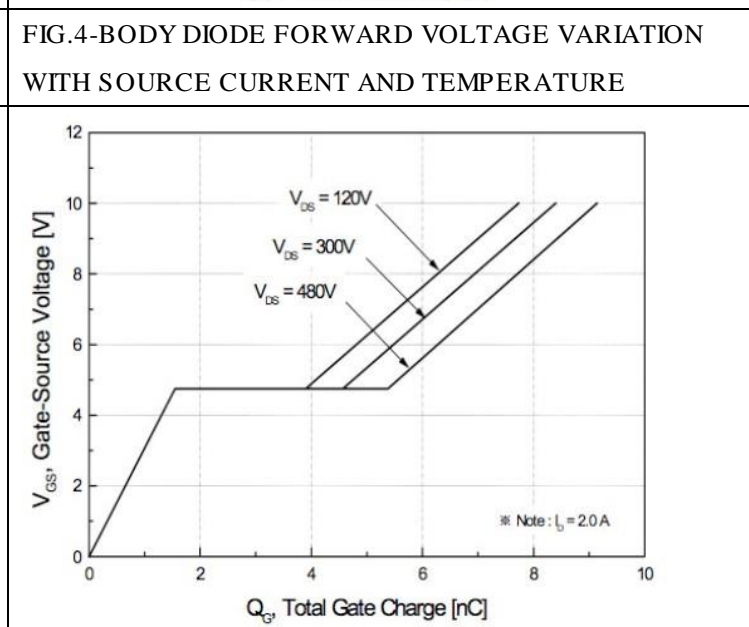


FIG.6-GATE CHARGE CHARACTERISTICS

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#### ■ Characteristics Curve

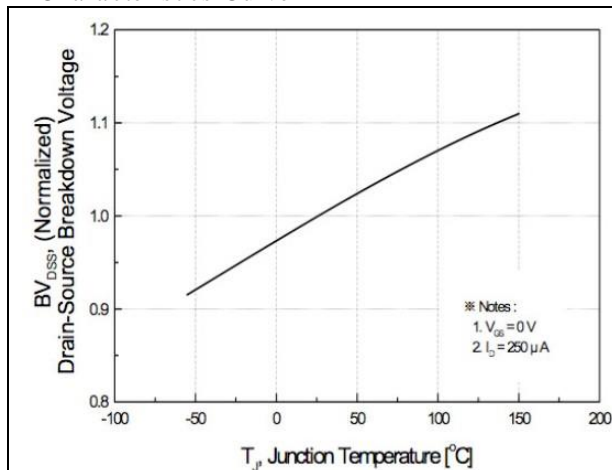


FIG.7-BREAKDOWN VOLTAGE VARIATION VS TEMPERATURE

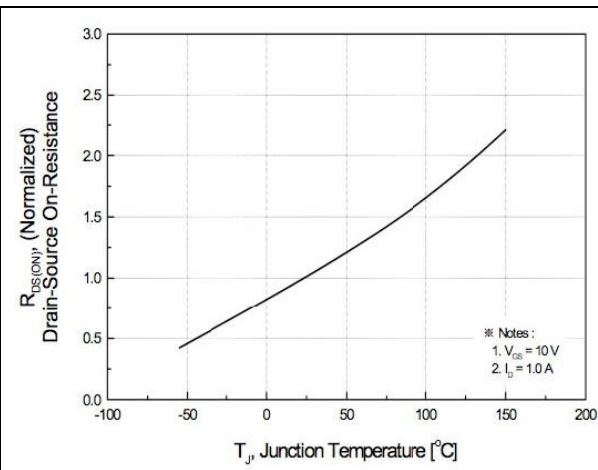


FIG.8-ON-RESISTANCE VARIATION VS TEMPERATURE

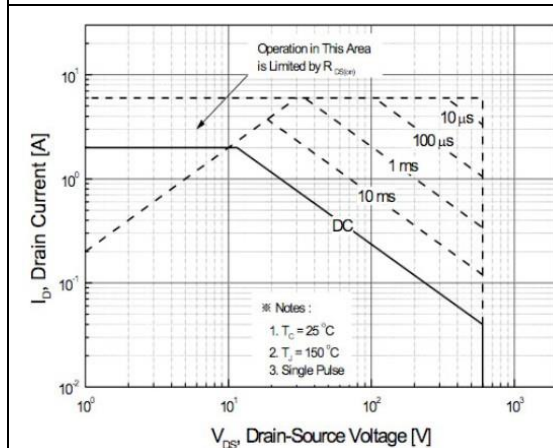


FIG.9-MAXIMUM SAFE OPERATING AREA

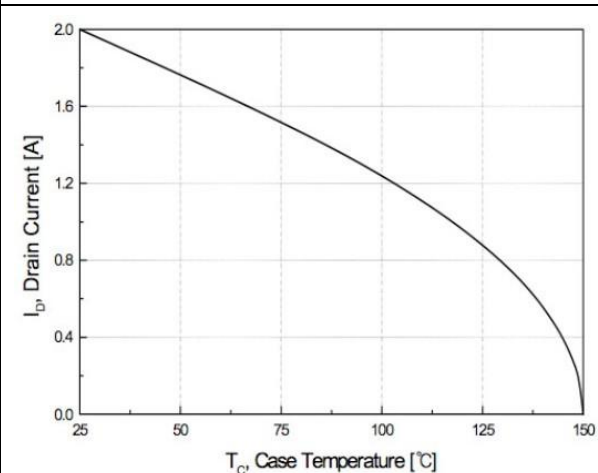


FIG.10-MAXIMUM DRAIN CURRENT VS CASE TEMPERATURE

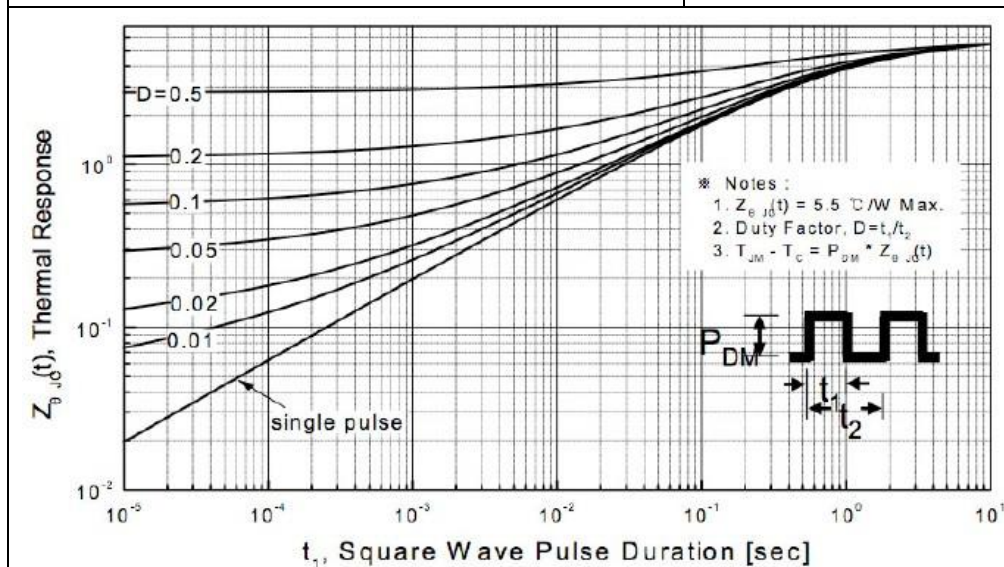


FIG.11-TRANSIENT THERMAL RESPONSE CURVE



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#### ■ Characteristics Test Circuit & Waveform

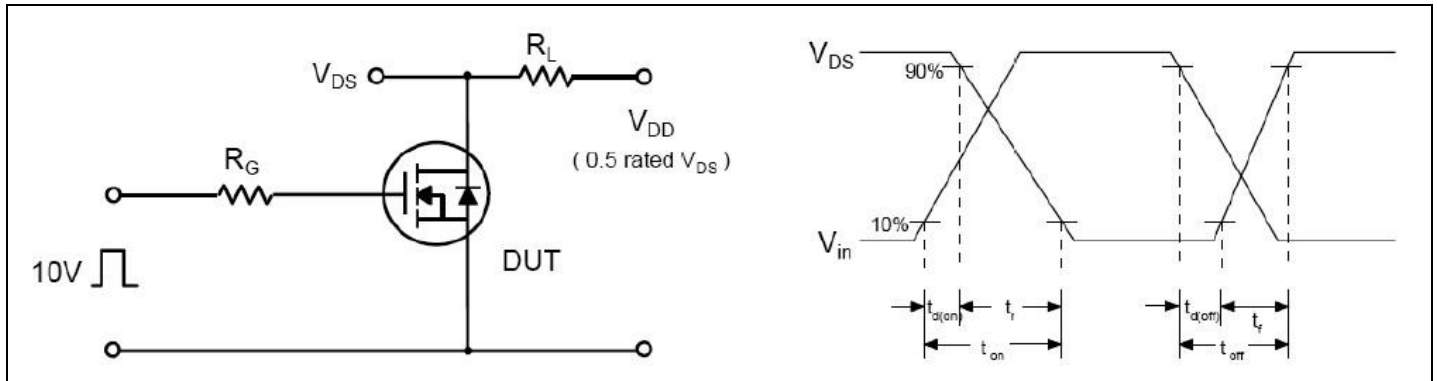


Fig 12. Resistive Switching Test Circuit & Waveforms

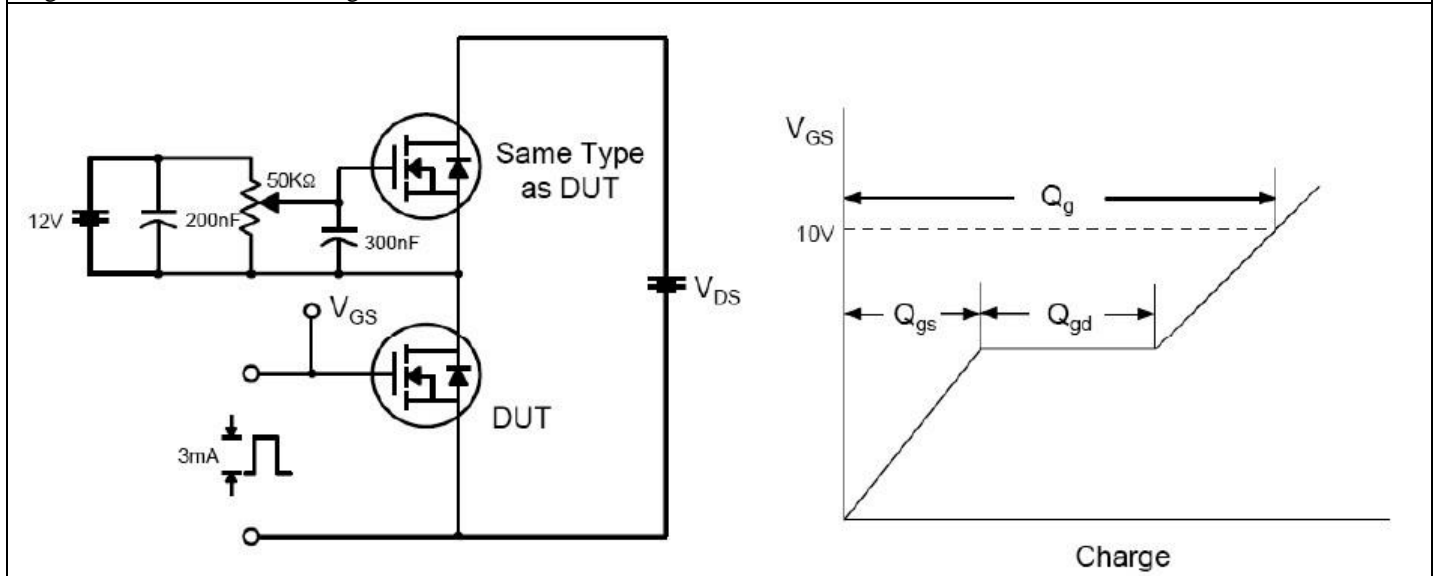


Fig 13. Gate Charge Test Circuit & Waveform

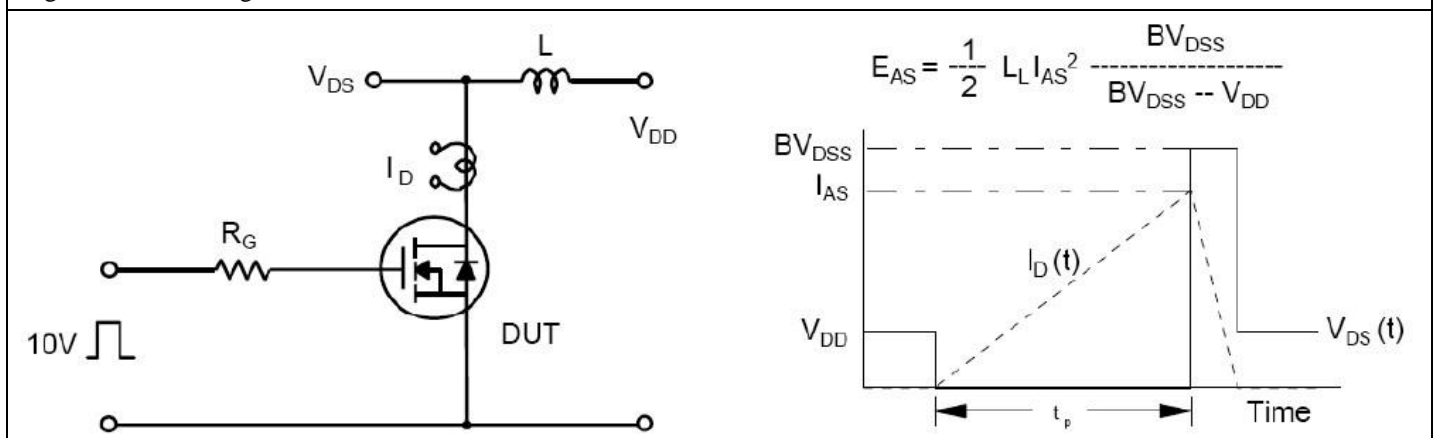


Fig 14. Unclamped Inductive Switching Test Circuit & Waveforms

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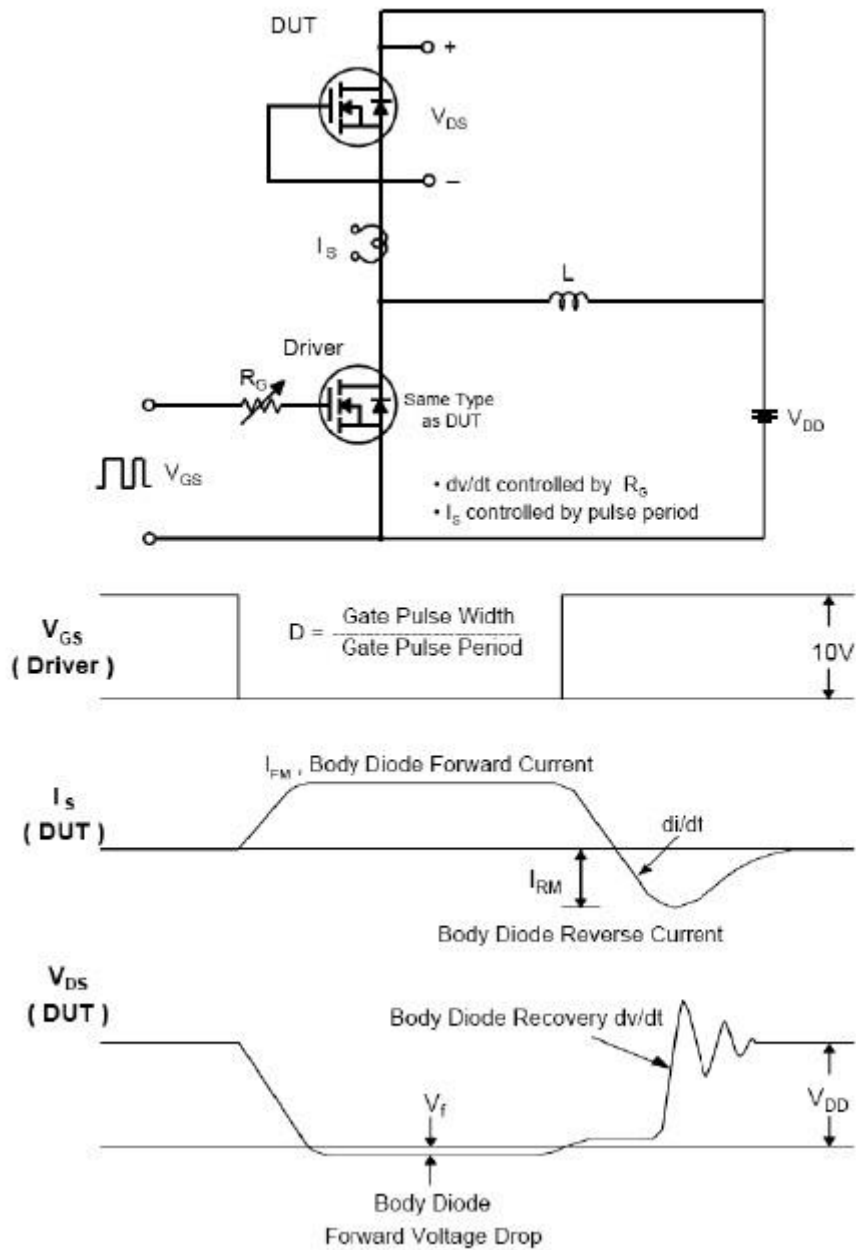


Fig 15. Peak Diode Recovery  $dv/dt$  Test Circuit & Waveforms

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